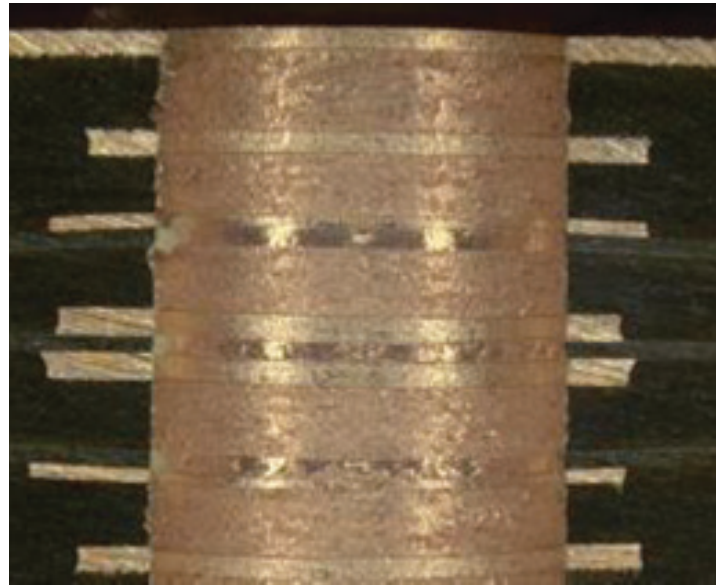


Via Dep 4550

Low Stress Electroless Copper Metallization

Stress Free Copper For Your Engineers and Your Difficult-to-Plate Materials

MacDermid Enthone's **Via Dep 4550** electroless copper system is the industry's choice primary metallization for difficult-to-plate substrates. The 4550 process offers superior adhesion on inert surfaces and difficult structural designs while maintaining structural integrity. The zero stress, blister free deposit for SAP, MSAP and Flex applications assures that your metallization needs on complicated hybrid devices can be met with ease.



KEY FEATURES

- Stress free copper deposit
- Environmentally friendly tartrate based plating solution
- Low operating temperature for reduced operating costs
- Compatibility with flex, rigid-flex, and rigid PCB designs
- Drop-in replacement to existing electroless copper line
- Passes IPC-TM-650 for thermal stress on plated through holes



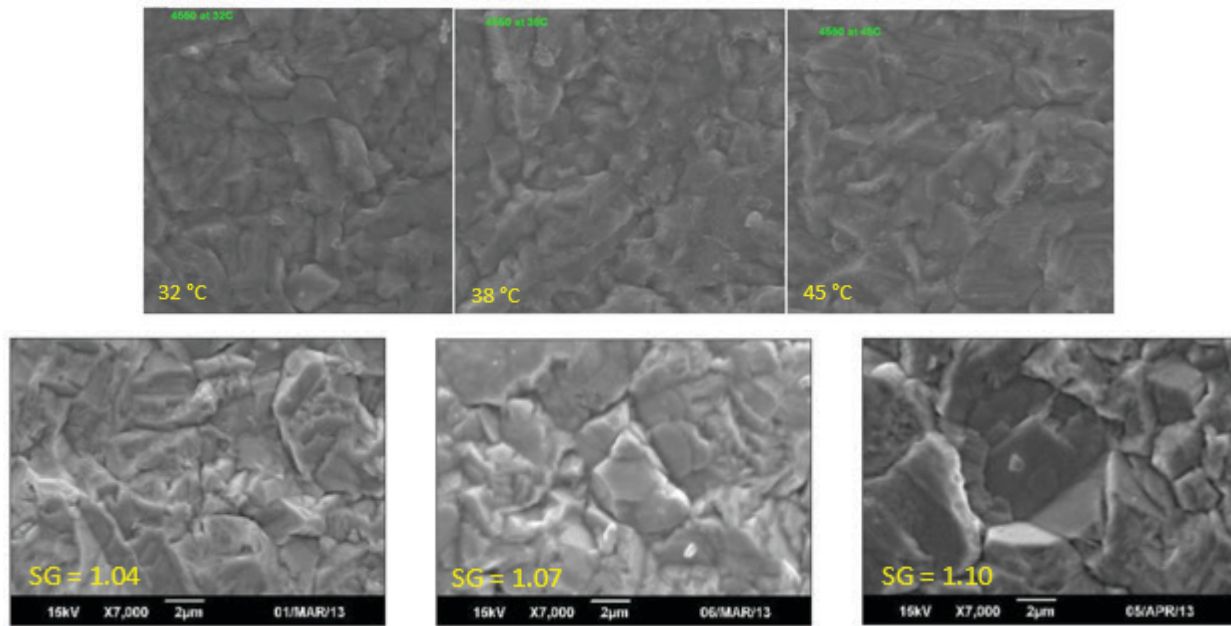
MacDermid Enthone

Via Dep 4550

Low Stress Electroless Copper Metallization

Stable and User Friendly, Consistent Deposit Properties Across a Huge Operating Window

Consistency is everything. In the production environment, yields are becoming more important than ever due to electronics content increasing considerably in our cars, medical devices, and homes. The Via Dep 4550 process provides the same highly adherent deposit whether it's processed with fresh chemistry, high or low temperatures, or over a wide range of materials.



Adhesion on a Wide Range of Exotic Materials



7 Mil Via on AP Material - Left: Conventional Electroless Copper, Right: Via Dep 4550

Conventional electroless copper baths lack the superior adhesion obtained with Via Dep 4550. A proprietary formulation allows for high performance metallization on flex, rigid-flex and rigid PCB materials, meaning that only one bath is needed for a large number of jobs.



macdermidalpha.com
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MacDermid Enthone is a product brand of MacDermid Alpha Electronics Solutions.